



(12) Patent Application Publication
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(43) **Pub. Date:** **Nov. 17, 2022**

(52) U.S. Cl.

(30) **Foreign Application Priority Data**

May 13, 2021 (JP) 2021-081908

Publication Classification

(51) **Int. Cl.**

H05K 3/34 (2006.01)

(57)

ABSTRACT

A circuit board includes an interconnect and an insulating layer that covers the interconnect. The interconnect includes a first interconnect that is formed to serve as a recognition mark of which planar shape is a predetermined shape. The insulating layer has a through-hole of which planar shape is variant and that penetrates the insulating layer in a thickness direction of the insulating layer such that an entire upper surface of the first interconnect is exposed. The through-hole includes a first through-hole of which planar shape is a predetermined shape and that penetrates the insulating layer in the thickness direction such that the entire upper surface of the first interconnect is exposed and a second through-hole that serves as part of an inner wall surface of the first through-hole and that penetrates the insulating layer in the thickness direction.

